



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Sectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-09-15
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA25P35-1U1M	812Q*6TAN25B	A	Z6HA	2017-09-15
Amount	UoM	Unit type	ST ECOPACK Grade	
2.40	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	1.6 - 1 - 0.6	2	flat	
Comment	Package: DFN.16.10.06-105-2L			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		

QueryList : California Prop65 list, dated 7th July 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.035	Leadframe	14583

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	812Q*6TAN25B				5000000.0	1000004.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.237	mg	supplier	die	Silicon (Si)	7440-21-3		0.217	mg	915612	90417
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	42194	4167
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	25316	2500
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	4220	417
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.003	mg	12658	1250
Leadframe	M-004 Copper and its alloys	0.697	mg	supplier	alloy	Copper (Cu)	7440-50-8		0.654	mg	938307	272500
				supplier	alloy	Nickel (Ni)	7440-02-0		0.024	mg	34433	10000
				supplier	alloy	Silicon (Si)	7440-21-3		0.004	mg	5739	1667
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.001	mg	1435	417
				supplier	alloy	Iron (Fe)	7439-89-6		0.001	mg	1435	417
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	5738	1667
				supplier	metallization	Nickel (Ni)	7440-02-0		0.008	mg	11478	3333
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	1435	417
Die attach	M-011 Other inorganic materials	0.032	mg	supplier	glue	Silver (Ag)	7440-22-4		0.024	mg	750000	10000
				supplier	glue	Butyl diethylene glycol acetate	124-17-4		0.003	mg	93750	1250
				supplier	glue	Bismaleimide resin	35325-39-4		0.002	mg	62500	833
				supplier	glue	High boiling methacrylate	Proprietary		0.001	mg	31250	417
				supplier	glue	Acrylic monomer	Proprietary		0.001	mg	31250	417
supplier	glue	Acrylate	Proprietary		0.001	mg	31250	417				
Bonding wire	M-008 Precious metals	0.021	mg	supplier	wires	Copper (Cu)	7440-50-8		0.021	mg	1000000	8750
Encapsulation	M-011 Other inorganic materials	1.413	mg	supplier	mold compound	Silica Fused	60676-86-0		1.320	mg	934183	550000
				supplier	mold compound	Epoxy Resin	25068-38-6		0.046	mg	32555	19167
				supplier	mold compound	Phenol Resin	29690-82-2		0.043	mg	30432	17917
				supplier	mold compound	Carbon Black	1333-86-4		0.004	mg	2830	1667